
Informacijski standard o komponentah Pinnacles 1.2 – PCIS vzorčni dokumenti

Pinnacles Component Information Standard 1.2 - PCIS Sample Documents

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English version

Pinnacles Component Information Standard 1.2

PCIS Sample Documents

This CENELEC Report has been prepared by the Technical Committee CENELEC TC 217, Electronic Design Automation (EDA). It was approved by the Technical Committee on 1996-12-09 and endorsed by the CENELEC Technical Board on 1998-08-01.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

This CENELEC Report has been produced by The Pinnacles Group (predominantly) and by CENELEC Technical Committee TC 217, Electronic Design Automation (EDA). The text of the draft, which was submitted to the CENELEC members for comments, was approved during the CLC/TC 217 meeting on 1996-12-09 and endorsed by the CENELEC Technical Board as R217-016 on 1998-08-01.

The Pinnacles Component Information Standard 1.2 (PCIS 1.2) was developed by members of the Pinnacles Group who collaborated towards internationally agreed standards in the area of electronic data book technology.

The original development of the PCIS standard was accomplished under the coordination of the Pinnacles Group, with members from five electronic component manufacturers who joined together to create a technical information exchange standard for use by the electronics industry. These original member companies have all been active members of the Silicon Integration Initiative, Inc. (Si2) electronic databook working group, and it was in conjunction with Si2 (then the CAD Framework Initiative, Inc.) activities that the original concept of the PCIS was developed. The original work of Hitachi America Limited, Intel, National Semiconductor, Philips Semiconductors, and Texas Instruments was extended when Hewlett-Packard, IBM Microelectronics, and Motorola joined the effort. Representatives of Hewlett-Packard, Hitachi America Limited, IBM Microelectronics, Intel, Motorola, Philips Semiconductors, and Texas Instruments currently serve as members of the Si2 Electronic Component Information Exchange (ECIX) Project Technical Advisory Board.

Additional information regarding tools, customers and related specifications may be found at <http://www.si2.org/ecix/>.

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General Introduction

Scope and object

The purpose of this European Prestandard is to model electric component data and to define an interchange format for that data (Electronic Data Book -EDB- standard) which is independent of the component supplier or the customers CAD environment.

The Pinnacles Component Information Standard (PCIS) is being developed to serve as a basis for the interchange of technical information about electronic components and to enable electronic component manufacturers to create and distribute a new form of compiled information, Electronic Data Books (EDBs), by electronic component manufacturers. An established, documented interchange standard is a necessary precursor for both of these tasks.

The PCIS principles and methodology may be applied to any kind of electric component, such as semiconductor devices, passive components, display components etc.

An interchange standard will enable companies to provide reusable technical data to customers and vendors. Currently, customers and vendors must rekey this data into their systems. Such rekeying is often an extremely inefficient, inaccurate, time-consuming, and costly process. The interchange standard will define ways to identify information elements so that customers and vendors can receive, process, and extract only the information they need.

In addition, manufacturers themselves will be able to identify, organize, and offer more useful information to customers through the implementation of Electronic Data Books. An EDB is a comprehensive set of information about one or more electronic components, including active and passive components, materials, and connectors. As the PCIS defines an EDB, it could include both the textual and graphic information currently published in databooks and datasheets and other computer-sensible data types such as CAD files, behavioral and functional models, and audio and video recordings. In short, an EDB could include all the data that a company wishes to provide to facilitate the design-in and support of an electronic component.

EDBs will increase the quality of product information by improving its accuracy, accessibility, and timeliness, as well as by enabling CAD integration. Such improvements will help customers realize benefits in product identification and selection, reduce design-in and qualification cycle-times, and improve product life-cycle management, among other benefits.

Structure of the Pinnacles Component Information Standard (PCIS)

This version of the PCIS describes only the SGML component of the developing interchange standard. This Tutorial and the accompanying parts are the first in a series of documents that will be necessary to support the standard. Other documentation, such as a physical packaging standard and graphics standards, will be developed and described in future efforts.

The Pinnacles Component Information Standard 1.2 is organized into four main parts:

- The PCIS Tutorial (document CENELEC R217-015: 1996 E) that describes the SGML architecture, intended use and application of the PCIS standard, and the rationale for the SGML design decisions
- The PCIS Tag Library (document CENELEC ENV 50247-1: 1996 E), that provides definitions of the information elements within electronic component documents;
- The SGML Declaration and SGML Document Type Definitions (document CENELEC ENV 50247-2: 1996 E) that describe the class of electronic components documents; and
- Tagged sample datasheets and datasheet fragments (document CENELEC R217-016: 1996 E).

Users of the Pinnacles Component Information Standard

PCIS will be used by many different types of users, with different benefits accruing to each type.

- Original Information Producers (OIPs) are companies who produce electronic components and materials and who supply information about those components to their customers.
- Value-Added Providers (VAPs) are companies who are in the business of adding value to a manufacturer's information (for example, models, simulations, etc.) and charging customers a fee for the value they add.
- Tool Suppliers supply hardware/software tools, such as CAD/CAE systems, publishing systems, database management systems, etc., to the industry.
- Equipment Producers (EPs) are companies or end users who design electronic products which include the components supplied by OIPs.

Each of these various types of users has a big stake in producing his work as efficiently as possible.

PCIS is designed to provide the most efficient transfer and re-use of component information possible, in both human- and computer-sensible form.

Relation to existing standards

PCIS has been built on existing standards activities where appropriate. PCIS 1.2 was placed in the public domain as an open standard.

The PCIS is an application of the meta-language of Standard Generalized Markup Language (ISO 8879:1986, also known as SGML). It is highly subject/content oriented, with a great deal of structure that can be used to describe the characteristics of electric components.

Clause 2.1 of the PCIS SGML Tutorial (document CENELEC R217-015:1996 E) describes the reasoning behind this decision and the benefits and drawbacks of SGML usage. SGML is a technical standard, and it is not expected that all readers of this document will necessarily understand the minutiae of its use and syntax. More detailed information about SGML is given at the informative annexes.

Currently there are no analogous standards activities for the electrical component industry that match the PCIS in scope, or applicability to the many phases of the business process and product life-cycle.

It is in no way the intention of the Pinnacles Group to duplicate existing standards, but rather to interoperate with related standards or standards activities such as:

- IEC SC3D: generating the IEC 1360 series of standards "Standards data element types with associated classification scheme for electric components";
- JEDEC;
- ISO 10303 (STEP);
- ESPRIT Project 22124-CIREP "Component Information Representation European Project";

The Pinnacles Group

The development of the Pinnacles Component Information Standard has been accomplished under the coordination of the Pinnacles Group, a non-affiliated standards working group with members from five electronic component manufacturers who joined together to create a technical information exchange standard for use by the electronic components industry. The member companies have all been active participants in the CAD Framework Initiative (CFI) Electronic Databook Working Group (EDB WG), and it was in conjunction with CFI activities that the original concept of the PCIS developed.

In discussion, it became clear to representatives of the various companies that creating such a standard would be difficult and time-consuming in a volunteer setting without expert assistance. As a result, a proposal was made to establish a privately-funded initiative that could address the CFI objectives as well as business issues outside the scope of the CFI. In April of 1993, after a year of preliminary work, Intel, National Semiconductor, Philips Semiconductors, and Texas Instruments signed an agreement to join forces under the working name "Pinnacles Group" to produce a technical information interchange standard to be called the Pinnacles Component Information Standard (PCIS). In July of 1993 Hitachi America Limited joined the Pinnacles Group as a full partner, more recently (1995) Hewlett Packard and IBM Microelectronics joined.

Soon after its inception in 1993, the European contribution to the development of PCIS became a part of CENELEC TC 217 WG 4, itself a part of the ESPRIT Project ESIP, ultimately resulting in the current documents as referenced in clause 1.2.

Informative references

The Pinnacles Electronic Data Book Project; The Pinnacles Group, <http://www.cfi.org/pinnacles/>

The SGML Handbook; Charles Goldfarb New York, Oxford University Press, 1990

Developing SGML DTDs; Eve Maler & Jeanne Andaloussi, Prentice Hall, 1996

The SGML Primer, SoftQuad, Inc. Toronto, SoftQuad, Inc. 1991

SGML seminars, tutorials, and publication sales Graphic Communications Association

The SGML Implementation Guide, Travis, Brian & Waldt, Dale, Springer-Verlag, 1995

IEC 1360-1 Standard data element types with associated classification scheme for electric components - part 1: Definitions - Principles and methods

[https://standards.iec.ch/catalog/standards/sist/faa9cfd1-aae0-4041-b0a0-](https://standards.iec.ch/catalog/standards/sist/faa9cfd1-aae0-4041-b0a0-802501feb104/sist-tp-ck-r217-016-2004)

IEC/48/FDIS Standard data element types with associated classification scheme for electric components - IEC reference collection of standard data element types, component classes and terms - (to become IEC 1360-4)

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Introduction to Samples

This section of PCIS samples is divided into two major parts: a formatted print samples and the same text tagged in PCIS 1.2 SGML.

The SGML versions of these documents are provided to illustrate the principles involved in applying these DTDs. They were created using SGML-aware authoring tools and have been parsed using a variety of SGML parsers

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Sample Datasheet

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INTEGRATED CIRCUITS

DATA SHEET

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PCF29F64
8 K x 8-bit static CMOS EEPROM
with PAGE-ERASE option

Preliminary specification
File under Integrated Circuits, IC10

January 1993

Philips Semiconductors



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